

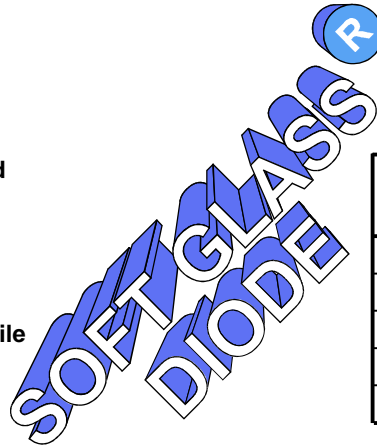
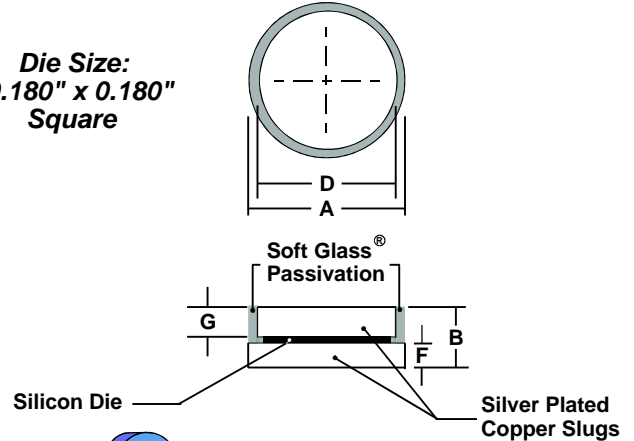
35 AMP OVERVOLTAGE TRANSIENT DISH DIODE

FEATURES

- VOID FREE VACUUM DIE SOLDERING FOR MAXIMUM MECHANICAL STRENGTH AND HEAT DISSIPATION
- PROPRIETARY *SOFT GLASS*[®] JUNCTION PASSIVATION FOR SUPERIOR RELIABILITY AND PERFORMANCE
- Large die for high power capability
- Very low forward voltage drop
- Built-in stress relief mechanism for die protection
- Silver plated substrates for corrosion resistance and superior soldeability
- Soldering temperature: 250 °C maximum
- Protects expensive automotive electronics and mobile equipment

MECHANICAL SPECIFICATION

Die Size:
 0.180" x 0.180"
 Square



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	5.33	5.46	0.210	0.215
B	2.03	2.16	0.080	0.085
D	4.70	4.83	0.185	0.190
F	0.64	0.76	0.025	0.030
G	0.96	1.09	0.038	0.043

MAXIMUM RATINGS & ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.

PARAMETER (TEST CONDITIONS)	SYMBOL	RATINGS	UNITS
Series Number		TVS3527D	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	23	VOLTS
Working Peak Reverse Voltage	V _{RWM}		
Maximum DC Blocking Voltage	V _{DC}		
Breakdown Voltage (I _R = 100 mA dc, T _c = 25 °C)	V _(BR)	24 Min / 32 Max	
Average Rectified Forward Current (Single phase, Resistive load, 60 Hz)	I _o	35	AMPS
Non-repetitive Peak Forward Surge Current (Half wave, Single phase, 60 Hz sine applied to rated load)	I _{FSM}	500	
Repetitive Peak Reverse Surge Current (Time constant = 10 mSec Duty cycle ≤ 1.0%, T _c = 25 °C)	I _{RSM}	110	
Instantaneous Forward Voltage (I _F = 80A @ 300 μSec pulse, T _c = 25 °C)	V _F	1.05 1.00 (Typical)	VOLTS
Maximum DC Reverse Current (V _R = 20V DC, T _c = 25 °C)	I _R	200	nA
Maximum Thermal Resistance, Junction to Lead (Note 1)	R _{θJC}	0.8	°C/W
Junction Operating & Storage Temperature Range	T _J , T _{STG}	-65 to +175	°C

Notes: 1) Single Side Cooled

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